

Product	Cat. #	Specific Gravity	Viscosity @ 25°C (CPS)	Tg (°C)	Modulus @ 25°C (Mpa)	CTE A1 (ppm/°C)	CTE A2 (ppm/°C)	Optimum Cure Schedule (°C)	Comments
EasyFILL® Conformal Coat	CC1001	1.15	110	120	25	70	170	60 min @ 160	Solvent based coating. High performance and adhesion properties. Other viscosity ranges available.
EdgeCONTROL®	SD502C	1.10	1000K	<20	1	130	250	90 min @ 90+ 60 min @ 150+ 60 min @ 160	Low modulus retention dam, low cure stress and low warpage. Thixotropic, co-curable with SF5002.
EdgeCONTROL®	SD5460	1.08	1000K	<20	1	130	250	90 min @ 90+ 60 min @ 150+ 60 min @ 160	Low modulus retention dam, low cure stress and low warpage. Thixotropic, co-curable with SF546B.
LoSTRESS™	SF5002	1.08	11K	<20	5	149	240	90 min @ 90+ 60 min @ 150+ 60 min @ 160	Low modulus, flame retardant low cure stress encapsulant
LoSTRESS™	SF54GB	1.25	30K	<20	1	130	250	90 min @ 100+ 60 min @ 150+ 60 min @ 160	Low modulus, non-toxic flame retardant, low cure stress encapsulant. Good aging resistance.
NoSWEEP™	EW2000	1.90	1000K	207	2000	14	35	UVA 7.5J/cm2	UV curable wire encapsulant. Low CTE, high modulus.
NoSWEEP™	EW2001	1.90	45K	207	2000	14	35	UVA 7.5J/cm2	Low viscosity version of EW2000.
NoSWEEP™	EW7072	1.80	115K	>180	14000	14	29	UVA 1J/cm2 @ >90 60 min @ 130+ 180 min @ 170	Wire bond encapsulant. UV or thermal cure. Low CTE, very high modulus. High dielectric strength.
NoSWEEP™	EW7073	1.67	250K	174	9000	23	63	UVA 1J/cm2 @ >90 60 min @ 130+ 180 min @ 175	Wire bond encapsulant. UV + thermal cure. Low CTE, very high modulus. High dielectric strength. Ring lock*
NoSWEEP™	EW8002	1.70	50K	160	2000	20	70	60 min @ 100+ 60 min @ 165+	Low viscosity version of EW8003.
NoSWEEP™	EW8003	1.70	250K	160	2500	18	50	90 min @ 100+ 60 min @ 165	Wire bond encapsulant, excellent adhesion.
OptiCLEAR®	SF5003	1.08	15.6K	40	125		200	UVA 7.5J/cm2 or 120 min @ 120+ 120 min @ 150	Optically clear, medium viscosity, low modulus encapsulant.
OptiCLEAR®	SF5011	1.08	95K	20	15		210	UVA 7.5J/cm2 or 120 min @ 120+ 120 min @ 150	Optically clear, high viscosity, low modulus encapsulant.
OptiCLEAR®	SF502A	1.08	4700	40	175		200	UVA 7.5J/cm2 or 120 min @ 120+ 120 min @ 150	Optically clear, low viscosity, low modulus encapsulant.
OptiCLEAR®	SF801A SF801B	1.20 1.00	1500 10	65 65	36 36	55 55	200 200	7 days @ RT or elevated temps	Optically clear 2 part epoxy. Excellent toughness and clarity.
StenSEAL®	ES8001	2.13	230K	>170	5000	17	45	90 min @ 60+ 30 min @ 90+ 60 min @ 125	Stencil applied high modulus, flame retardant encapsulant.
ZipCURE™	DC1001	4.43	75K	55	10	40	140	15 min @ 185	Die attach adhesive, silver filled, low cure stress.
ZipCURE™	DC2000	1.2	20K	130	15	60	170	30 min @ 150	Die attach adhesive, non-conductive, high adhesion.

*patented technology

Solving Electronic Assembly & Manufacturing Issues with Unique Chemicals & Polymers